TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (High Speed U-MOSII)

# TPC8105-H

High Speed and High Efficiency DC-DC Converters Lithium Ion Battery Applications Notebook PCs

Portable Equipment Applications

• Small footprint due to small and thin package

• High speed switching

• Small gate charge : Qg = 32 nC (typ.)

• Low drain-source ON resistance :  $RDS(ON) = 20 \text{ m}\Omega \text{ (typ.)}$ 

• High forward transfer admittance :  $|Y_{fs}| = 12 \text{ S (typ.)}$ 

• Low leakage current :  $IDSS = -10 \mu A (max) (VDS = -30 V)$ 

• Enhancement-mode :  $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{ mA})$ 

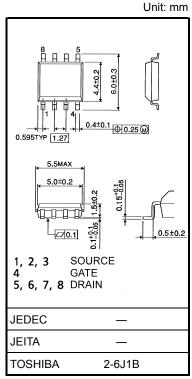
#### Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Drain-gate voltage (R	k <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	-30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	-7	Α	
Diam current	Pulse (Note 1)	$I_{DP}$	-28		
Drain power dissipati	on (t = 10 s) (Note 2a)	$P_{D}$	2.4	W	
Drain power dissipation	on (t = 10 s) (Note 2b)	P <sub>D</sub>	1.0	W	
Single pulse avalanch	ne energy (Note 3)	E <sub>AS</sub>	63.7	mJ	
Avalanche current		I <sub>AR</sub>	-7	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.24	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	-55 to 150	°C	

Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

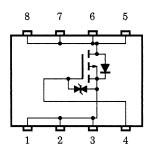
This transistor is an electrostatic sensitive device. Please handle with caution.

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Weight: 0.080 g (typ.)

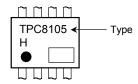
### **Circuit Configuration**



#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

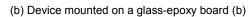
## Marking (Note 5)

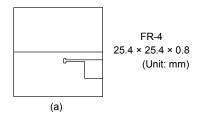


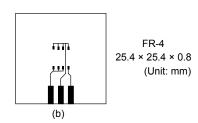
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

(a) Device mounted on a glass-epoxy board (a)







Note 3:  $V_{DD}$  = -24 V,  $T_{ch}$  = 25°C (initial), L = 1.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = -7 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature.

Note 5: on lower left of the marking indicates Pin 1.

shows Lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: january to december are denoted by letters A to L respectively)

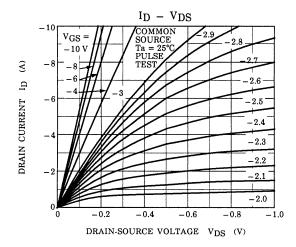


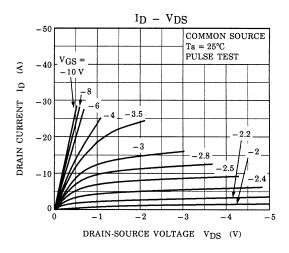
# **Electrical Characteristics (Ta = 25°C)**

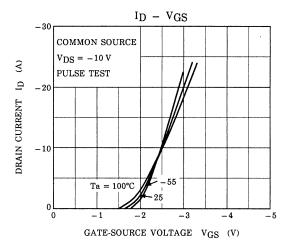
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μA	
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V	_	_	-10	μA	
Drain-source breakdown voltage		V <sub>(BR) DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V	
		V <sub>(BR) DSX</sub>	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15		_	v	
Gate threshold	voltage	$V_{th}$	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	٧	
Drain-source O	N resistance	R <sub>DS (ON)</sub>	$V_{GS} = -4 \text{ V}, I_D = -3.5 \text{ A}$	_	34	60	mΩ	
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS} = -10 \text{ V}, I_D = -3.5 \text{ A}$	_	20	40	mt2	
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -3.5 A	5.9	12	_	S	
Input capacitano	ce	C <sub>iss</sub>			1440	_		
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	330	_	pF	
Output capacitance		C <sub>oss</sub>		_	485	_		
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $OV$ $I_{D} = -3.5 \text{ A}$ $V_{OUT}$	_	10	_		
	Turn-on time	t <sub>on</sub>	$V_{OUT}$ $R_{L} = 4.3 \Omega$ $V_{DD} = -15 V$ $Duty \le 1\%, t_{W} = 10 \mu s$		18	_	ns	
	Fall time	t <sub>f</sub>			50	_	113	
	Turn-off time	t <sub>off</sub>		l	140	l		
Total gate charge (Gate-source plus gate-drain)		$Q_{g}$		_	32	_		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx -24 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7 \text{ A}$		23	_	nC	
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	8	_		

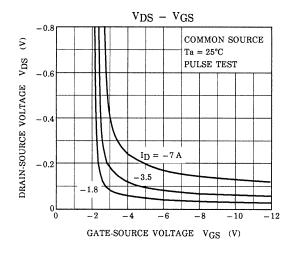
## Source-Drain Ratings and Characteristics (Ta = 25°C)

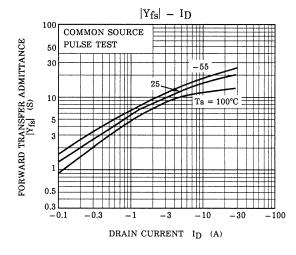
Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	-	_	_	-28	А
Forward voltage	(diode)	V <sub>DSF</sub>	$I_{DR}$ = -7 A, $V_{GS}$ = 0 V	_	_	1.2	V

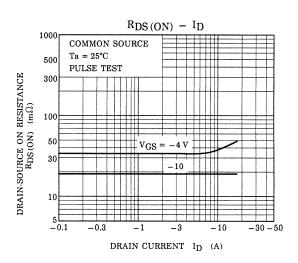




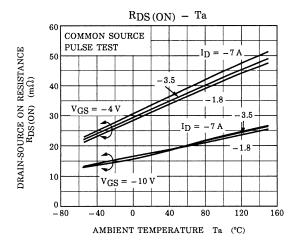


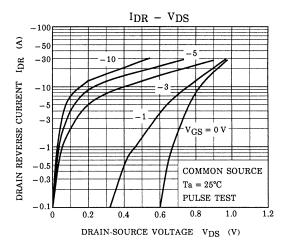


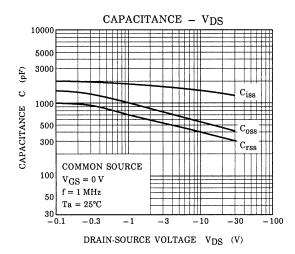


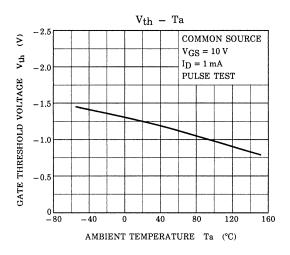


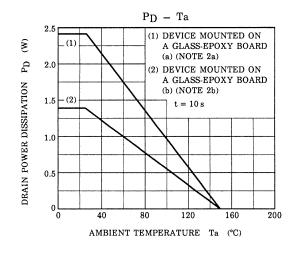
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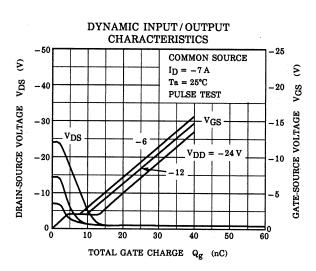




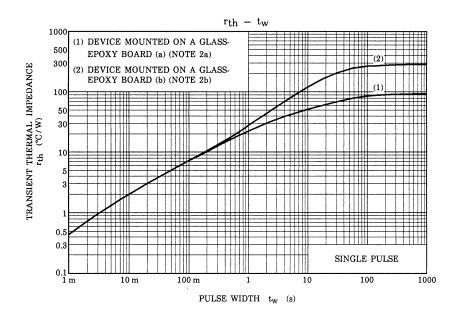


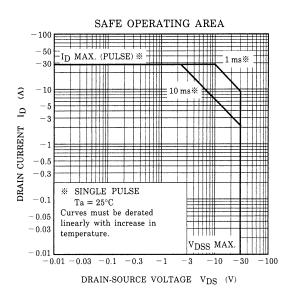


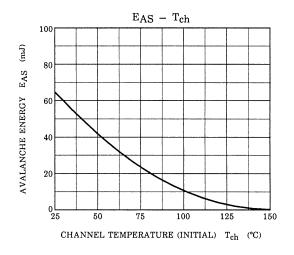


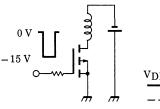


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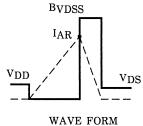








TEST CIRCUIT



$$\begin{split} &T_{Ch}=25^{\circ}C~(Initial)\\ &Peak~I_{AR}=-7~A,~R_{G}=25~\Omega\\ &V_{DD}=-24~V,~L=1.0~mH \end{split}$$

$$\begin{array}{l} T_{ch} = 25^{\circ} C \; (Initial) \\ Peak \; I_{AR} = -7 \; A, \; R_G = 25 \; \Omega \end{array} \quad E_{AS} = \frac{1}{2} \cdot L \; \cdot I^2 \cdot (\frac{BVDSS}{BVDSS - VDD}) \end{array}$$

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